

CGW®-2/2-Y (A/B)

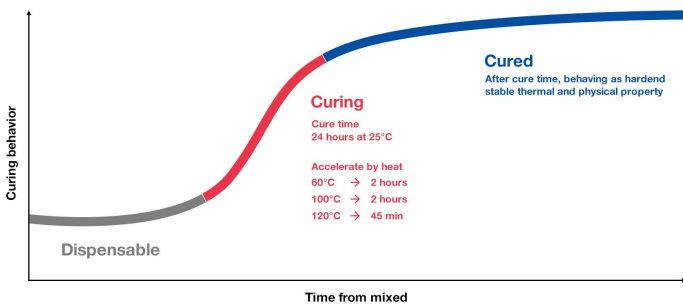
Description

CGW® series is a 2-part liquid silicone thermally conductive Gap Filler, curable at room temperature within 24 hours.

During the assembly process, the softness of the uncured compound applies almost zero stress on electronic components, PCBs and cabinets. CGW-2/2-Y offers one of the lowest molecular siloxane content level in the market. This enables the usage of the product close to contact points like switches and connectors in electronic devices.

Dispensable silicone type

CGW® series 2-part components



The 2-component stress reacting type provides outstanding productivity and formability

Features

- Thermal conductivity: 2.0 W/m·K
- Low specific gravity: 1.95
- Two-part, liquid gap filling, dispensable material
- Room temperature curable
- Accelerate curing time by applying temperature
- High thixotropic, holding three-dimensional shape
- Low stress, easy squeezing

Application

- Electronics devices
- EV / PHEV / HV battery assemblies
- Inverter / converter
- Optics (camera, LED modules)
- Medical electronics

Typical properties

Mixing ratio	1:1
Color(A)	CGW-2: Green CGW-2-Y: Yellow
Color(B)	White
Viscosity(A)*	240 Pa·s
Viscosity(B)*	220 Pa·s
Specific gravity(A)	1.95
Specific gravity(B)	1.95
Pot life at 25°C* (Up to twice of initial viscosity)	≥ 2hrs.
Cure time at 25°C	≤ 24hrs.
Thermal conductivity (ASTM D 5470)	2.0 W/m·K
Hardness (Shore00)	50
Flame rating (UL94)	V0
Operating temperature	-40 ~ 150°C
Volume resistance	≥ 1x10 ¹⁰ Ω
Breakdown voltage	≥ 10kV/mm

*Viscosity measured by Brookfield DV-E, SC-14, 10rpm

Packaging

- Dual cartridge (25cc x2, 100cc x2, 200cc x2)
- 330cc cartridge kit
- 600cc cartridge kit
- 25kg & 35kg pail kit

*Only same lot number of A and B may be processed together

Storage

Store in dry and cool place (1~30°C) and not exposed to direct sunlight. Keep away from heat, flame and vibrating machine. Best to use shortly after receiving to avoid the risk of filler sedimentation.

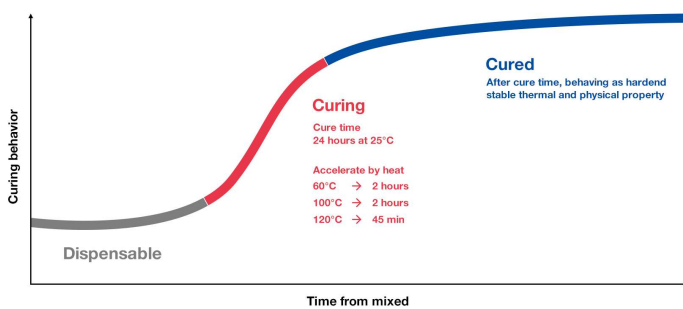
CGW® -3.6 (A/B)

Description

CGW® series is a 2-part liquid silicone thermally conductive Gap Filler, curable at room temperature within 24 hours. During the assembly process, the softness of the uncured compound applies almost zero stress on electronic components, PCBs and cabinets. CGW-3.6 offers one of the lowest molecular siloxane content level in the market. This enables the usage of the product close to contact points like switches and connectors in electronic devices.

Dispensable silicone type

CGW® series 2-part components



The 2-component stress reacting type provides outstanding productivity and formability

Features

- Thermal conductivity: 3.6 W/m·K
- Two-part, liquid gap filling, dispensable material
- Room temperature curable
- Accelerate curing time by applying temperature
- High thixotropic, holding three-dimensional shape
- Low stress, easy squeezing
- Specific gravity: 2.85

Application

- Electronics devices
- EV / PHEV / HV battery assemblies
- Inverter / converter
- Optics (camera, LED modules)
- Medical electronics

Typical properties

Mixing ratio	1:1
Color (A)	Light blue
Color (B)	White
Viscosity (A)*	260 Pa·s
Viscosity (B)*	230 Pa·s
Specific gravity (A)	2.85
Specific gravity (B)	2.85
Pot life at 25°C* (Up to twice of initial viscosity)	≥ 2hrs.
Cure time at 25°C	≤ 24hrs.
Thermal conductivity (ASTM D 5470)	3.6
Hardness (Type OO)	40
Flame rating (UL94)(≥0.15t)	V-0
Operating temperature	-40 ~ 150°C
Volume resistance	≥1x10 ¹⁰ Ω
Breakdown voltage	≥10kV/mm

*Viscosity measured by Brookfield DV-E, SC-14, 10rpm

Packaging

- Dual cartridge (25cc x2, 100cc x2, 200cc x2)
- 330cc cartridge kit
- 600cc cartridge kit
- 25kg & 35kg pail kit

*Only same lot number of A and B may be processed together

Storage

Store in dry and cool place (1~30°C) and not exposed to direct sunlight. Keep away from heat, flame and vibrating machine. Best to use shortly after receiving to avoid the risk of filler sedimentation.

For more information please reach out to mobility@nagase.eu

NAGASE (EUROPA) GmbH, Werdener Strasse 4, 40227 Düsseldorf, Germany, Tel: 0049 (0)211 866200

All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.

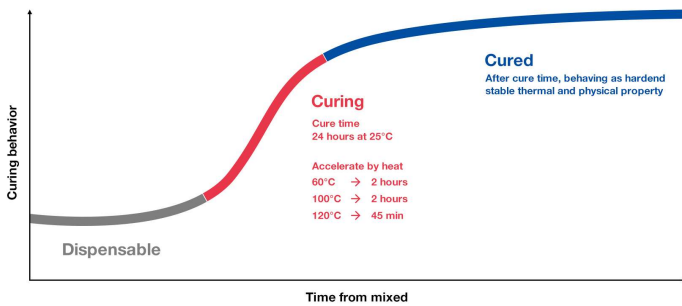
CGW® -3LW (A/B)

Description

CGW-3LW is a 2-part Gap Filler offering extremely low specific gravity with 3W/m·K thermal conductivity. This material is ideal for high volume using application or to concern total weight of application such as Li-ion battery, converter or inverter. The curing is completed within 24hrs, During the assembly process, the softness of the uncured compound applies almost zero stress on electronic components. CGW-3LW offers one of the lowest molecular siloxane content level in the market. This enables the usage of the product close to contact points like switches and connectors in electronic devices.

Dispensable silicone type

CGW® series 2-part components



The 2-component stress reacting type provides outstanding productivity and formability

Features

- Thermal conductivity: 3 W/m·K
- Low specific gravity: 2.20
- Two-part, liquid gap filling, dispensable material
- Room temperature curable
- Accelerate curing time by applying temperature
- High thixotropic, holding three-dimensional shape
- Low stress, easy squeezing

Application

- Electronic devices
- EV / PHEV / HV battery assembly
- Inverter / converter
- Optics (camera, LED modules)
- Medical electronics

Typical properties

Mixing ratio	1:1
Color (A)	Light blue
Color (B)	White
Viscosity (A)*	300 Pa·s
Viscosity (B)*	280 Pa·s
Specific gravity (A)	2.20
Specific gravity (B)	2.20
Pot life at 25°C* (Up to twice of initial viscosity)	> 2hrs.
Cure time at 25°C	< 24hrs.
Thermal conductivity (ASTM D 5470)	3.0
Hardness (Shore00)	55
Flame rating (UL94)	V0
Operating temperature	-40 ~ 150°C
Volume resistance	$\geq 1 \times 10^{10} \Omega \text{ cm}$
Breakdown voltage	$\geq 10 \text{ kV/mm}$

*Viscosity measured by Brookfield DV-E, SC-14, 10rpm

Packaging

- Dual cartridge (25cc x2, 100cc x2, 200cc x2)
- 330cc cartridge kit
- 600cc cartridge kit
- 25kg & 35kg pail kit

*Only same lot number of A and B may be processed together

Storage

Store in dry and cool place (1~30°C) and not exposed to direct sunlight. Keep away from heat, flame and vibrating machine. Best to use shortly after receiving to avoid the risk of filler sedimentation.

For more information please reach out to mobility@nagase.eu

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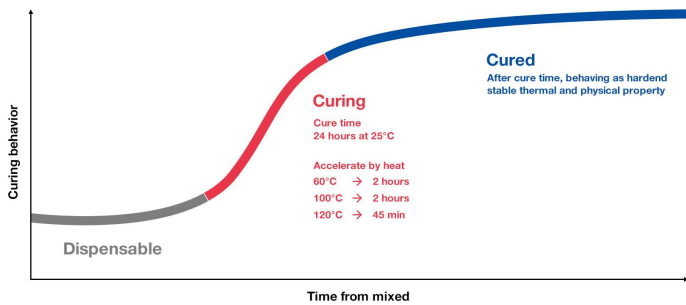
CGW® -4.5 (A/B)

Description

CGW® series is a 2-part liquid silicone thermally conductive Gap Filler, curable at room temperature within 24 hours. During the assembly process, the softness of the uncured compound applies almost zero stress on electronic components, PCBs and cabinets. CGW-4.5 offers one of the lowest molecular siloxane content level in the market. This enables the usage of the product close to contact points like switches and connectors in electronic devices.

Dispensable silicone type

CGW® series 2-part components



The 2-component stress reacting type provides outstanding productivity and formability

Features

- Two-part, liquid gap filling, dispensable material
- Room temperature curable
- Accelerate curing time by applying temperature
- High thixotropic, holding three-dimensional shape
- Low stress, easy squeezing
- No oil bleeding in various environment

Application

- Electronics device
- EV / PHEV / HV battery assembly
- Inverter / converter
- Optics (camera, LED modules)
- Medical electronics

Typical properties

Mixing ratio	1:1
Color (A)	Beige
Color (B)	White
Viscosity (A)*	250 Pa·s
Viscosity (B)*	250 Pa·s
Specific gravity (A)	3.15
Specific gravity (B)	3.15
Pot life at 25°C* (Up to twice of initial viscosity)	≥ 2hrs.
Cure time at 25°C	≤ 24hrs.
Thermal conductivity (ASTM D 5470)	4.5W/(m·K)
Hardness (type OO)	55
Flame rating (UL94)(≥0.15t)	V-0
Operating temperature	-40 ~ 150°C
Volume resistance	≥1x10 ¹⁰ Ω
Breakdown voltage	≥10kV/mm

*Viscosity measured by Brookfield DV-E, SC-14, 10rpm

Packaging

- Dual cartridge (25cc x2, 100cc x2, 200cc x2)
 - 330cc cartridge kit
 - 600cc cartridge kit
 - 25kg
- *Only same lot number of A and B may be processed together

Storage

Store in dry and cool place (1~30°C) and not exposed to direct sunlight. Keep away from heat, flame and vibrating machine. Best to use shortly after receiving to avoid the risk of filler sedimentation.